

## N-Channel 100 V (D-S) MOSFET

### PRODUCT SUMMARY

$BV_{DSS}$	100V
$R_{DS(on)(MAX.)}$	0.0115 $\Omega$
$I_D$	70A

### FEATURES

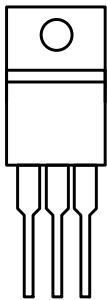
- SGT technology power supply Power MOSFET
- 100 %  $R_g$  and UIS Tested



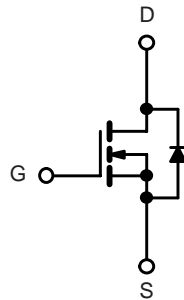
### APPLICATIONS

- Battery protection
- Load switch
- Uninterruptible power supply

### TO-220AB



G D S  
Top View



N-Channel MOSFET

### Absolute Maximum Ratings ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current@10V	$I_D$	$T_C = 25\text{ }^\circ\text{C}$	70
		$T_C = 100\text{ }^\circ\text{C}$	45
Pulsed Drain Current	$I_{DM}$	280	A
Single Pulse Avalanche Energy	$E_{AS}$	110	mJ
Total Power Dissipation	$P_D$	100	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	TYP.	MAX.	Unit
Thermal resistance, junction-to-ambient	$R_{\theta JA}$	-	64	$^\circ\text{C} / \text{W}$
Thermal resistance, junction-to-case	$R_{\theta JC}$	-	1.25	

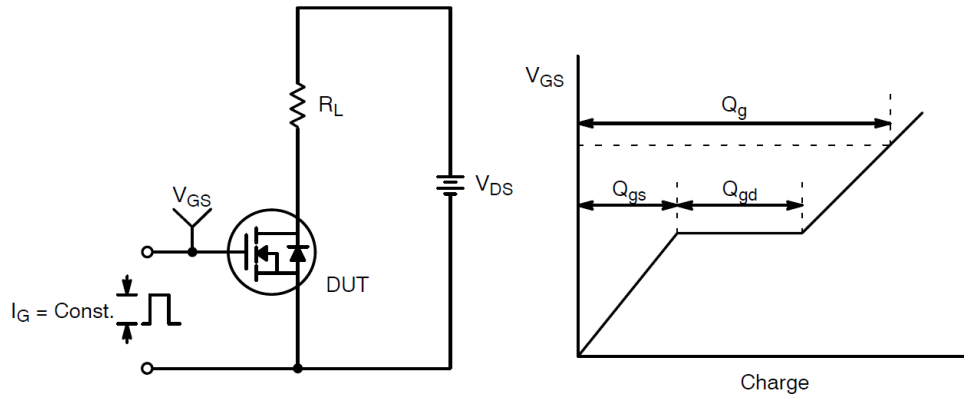
**Electrical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\ \mu\text{A}$	100	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 100\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$	1.2		2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ , $I_D = 20\text{ A}$	-	0.0095	0.0115	$\Omega$
		$V_{GS} = 4.5\text{ V}$ , $I_D = 15\text{ A}$	-	0.0105	0.013	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 50\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$	-	1370	-	pF
Output Capacitance	$C_{oss}$		-	453	-	
Reverse Transfer Capacitance	$C_{rss}$		-	13.1	-	
<b>Switching Characteristics</b>						
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	-	0.48	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{DS} = 50\text{ V}$ , $V_{GS} = 10\text{ V}$ , $I_D = 10\text{ A}$	-	31.5	-	nC
Gate-Source Charge	$Q_{gs}$		-	3.51	-	
Gate-Drain Charge	$Q_{gd}$		-	7.65	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 50\text{ V}$ , $I_D \cong 50\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_G = 4\ \Omega$	-	18	-	nS
Rise Time	$t_r$		-	12	-	
Turn-Off Delay Time	$t_{d(off)}$		-	42	-	
Fall Time	$t_f$		-	8	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$I_S = 10\text{ A}$ , $V_{GS} = 0\text{ V}$	-	-	1.2	V
Continuous Source-Drain Diode Current	$I_S$	$T_J = 25^\circ\text{C}$	-	-	70	A
Reverse Recovery Charge	$Q_{rr}$	$T_J = 25^\circ\text{C}$ , $I_F = 10\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$	-	189	-	nC
Reverse Recovery Time	$t_{rr}$		-	105	-	ns

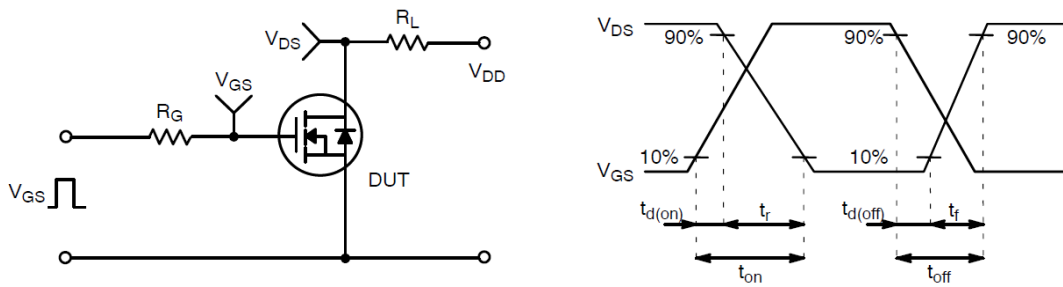
**Notes:**

- a. Repetitive rating; pulse width limited by maximum junction temperature  
b.  $V_{DD}=50\text{V}$ ,  $L=0.3\text{mH}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$

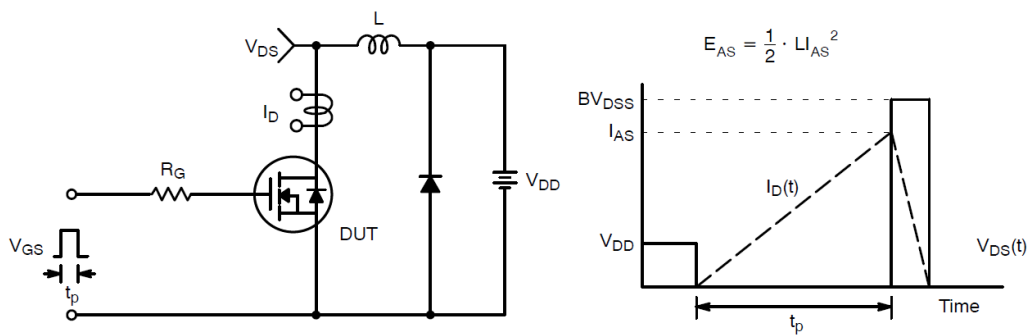
**Test circuit and Waveform**



**Gate Charge Test Circuit & Waveform**

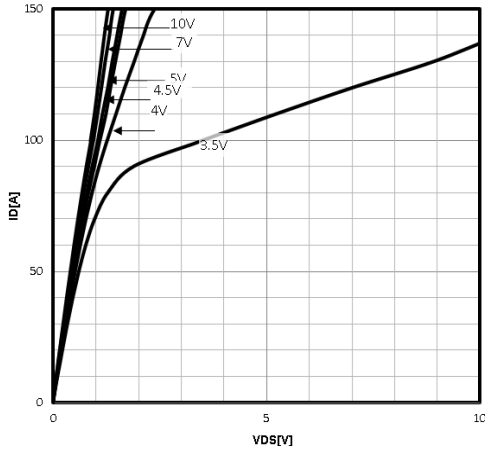


**Resistive Switching Test Circuit & Waveforms**

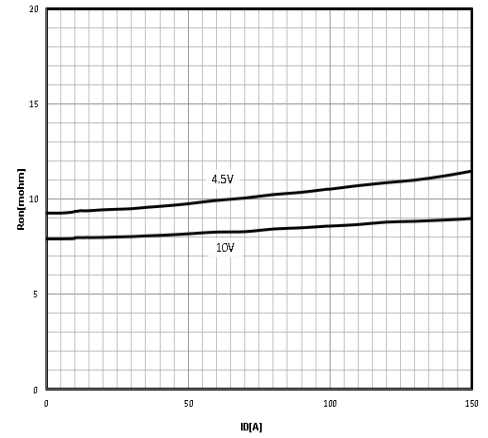


**Unclamped Inductive Switching Test Circuit & Waveforms**

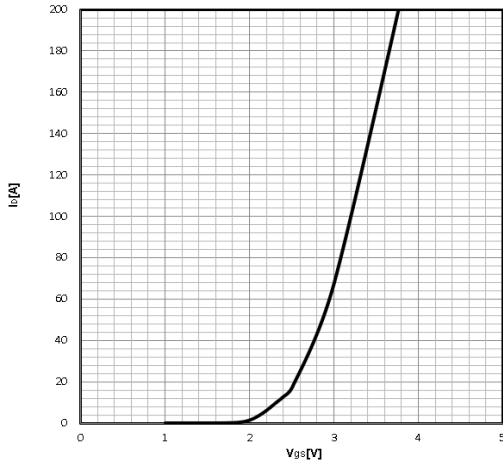
**TYPICAL CHARACTERISTICS** (25 °C unless noted)



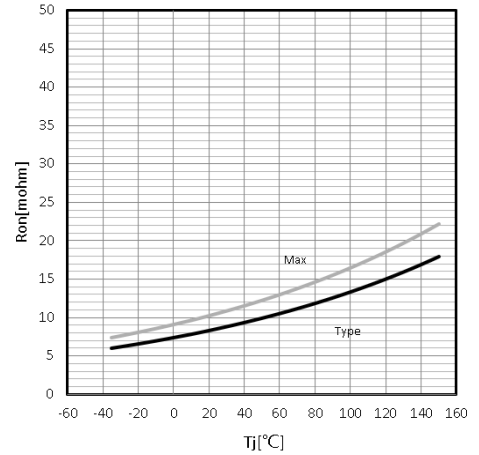
$I_D = f(V_{DS})$   
**Typ. output characteristics**



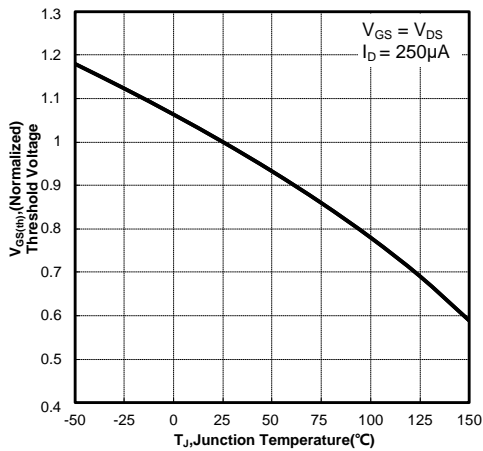
$R_{DS(on)} = f(I_D)$   
**Typ. drain-source on resistance**



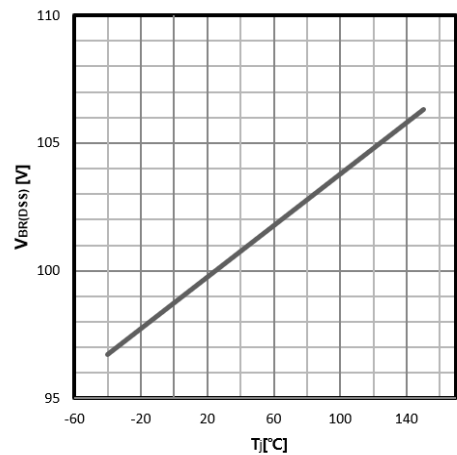
**Typ. transfer characteristics**



**Temperature dependence of  $R_{DS(on)}$**

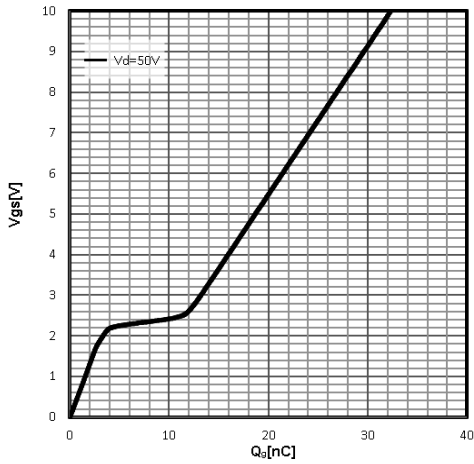


$V_{TH} = f(T_J); I_D = 250 \mu A$   
**Gate Threshold Voltage**



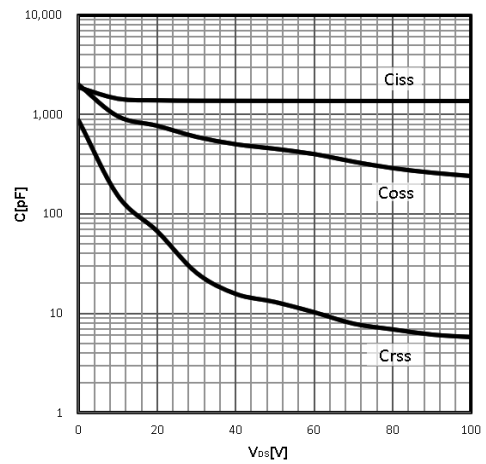
$V_{BR(DSS)} = f(T_J); I_D = 250 \mu A$   
**Drain-source breakdown voltage**

## TYPICAL CHARACTERISTICS (25 °C unless noted)



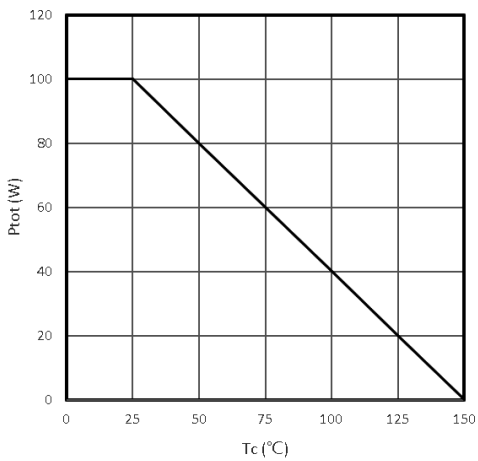
$$V_{GS} = f(Q_g) ; I_D = 10A$$

Typ. gate charge



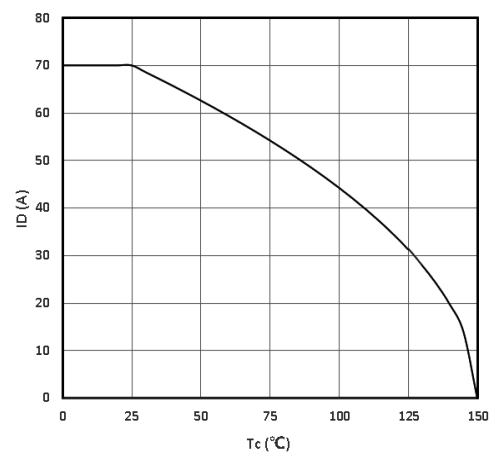
$$C = f(V_{DS}) ; V_{GS} = 0V ; f = 1MHz$$

Typ. capacitances



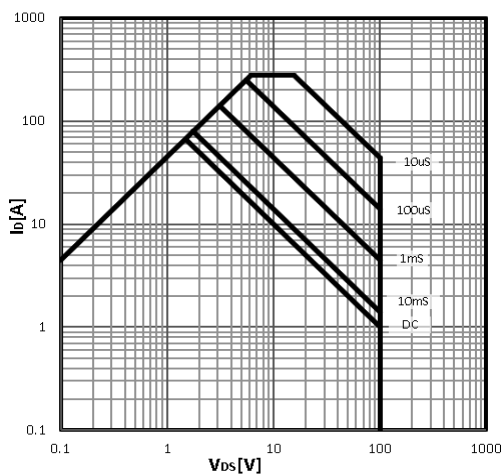
$$P_{tot} = f(T_c)$$

Power Dissipation



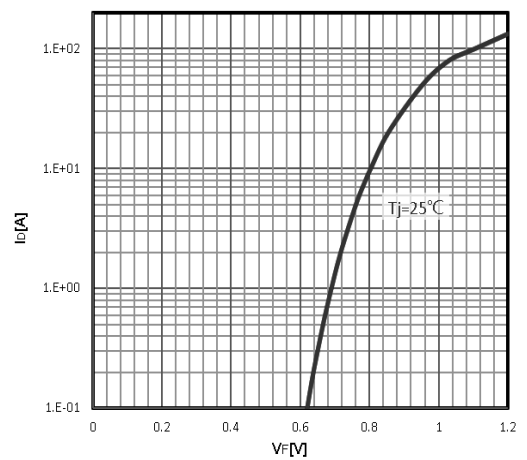
$$I_D = f(T_c)$$

Maximum Drain Current



$$I_D = f(V_{DS})$$

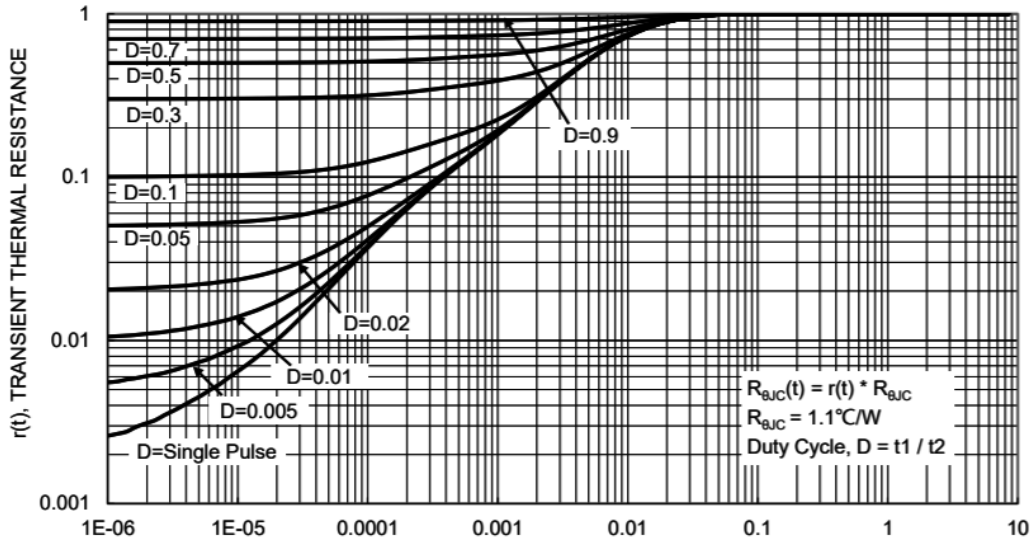
Safe operating area



$$I_F = f(V_{GS})$$

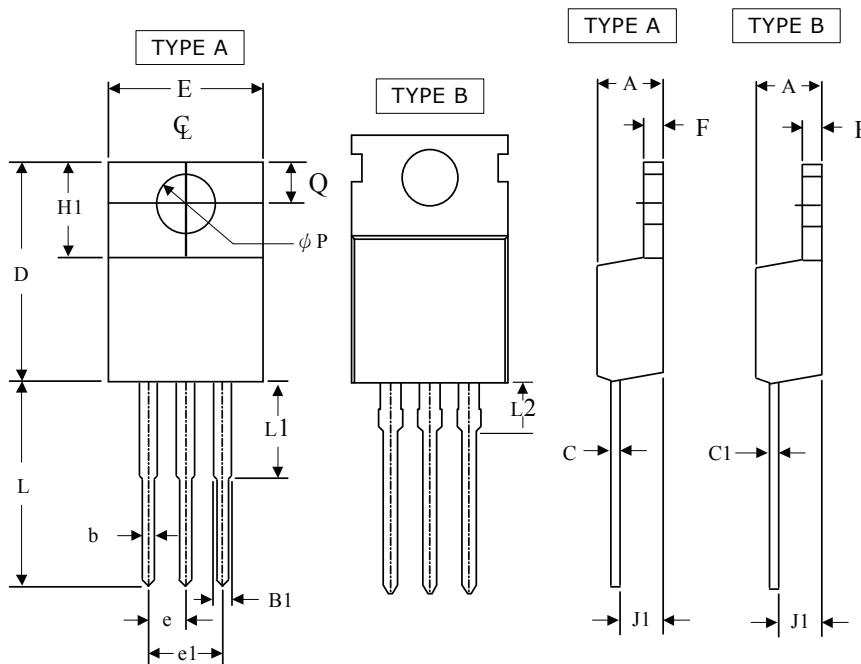
Body Diode Forward Voltage Variation

**TYPICAL CHARACTERISTICS** (25 °C unless noted)



$Z_{thJC} = f(t_p)$   
**Max. transient thermal impedance**

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SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.320	4.826	0.170	0.190
B1	1.143	1.778	0.045	0.070
b	0.610	0.910	0.024	0.036
c	0.356	0.530	0.014	0.021
c1	0.45	0.61	0.018	0.024
D	14.224	16.510	0.560	0.650
E	9.652	10.668	0.380	0.420
e	2.540 BSC		0.100 BSC	
e1	5.080 BSC		0.200 BSC	
F	1.220	1.397	0.048	0.055
H1	5.842	6.858	0.230	0.270
J1	2.032	2.921	0.080	0.115
L	12.700	14.732	0.500	0.580
L1	3.400	4.000	0.134	0.150
L2	2.70	3.20	0.106	0.126
$\phi P$	3.530	4.090	0.139	0.161
Q	2.540	3.429	0.100	0.135